



Press Release

### **Unisem Announces Selection of Teradyne J750Ex for Consumer Digital Testing**

**Kuala Lumpur, Malaysia – July 11, 2011** – Unisem announces the availability of Teradyne® J750Ex digital instrumentation for program development and production test at its facility in Sunnyvale, California. Unisem is a long-time J750 customer and recently adopted J750Ex digital instrumentation to extend the range of semiconductor test applications it can serve with the J750 platform. In addition to its Sunnyvale, California location, Unisem has multiple J750 systems installed in the UK, China and Southeast Asia.

The J750Ex instrumentation includes 200MHz digital test capability, enables faster test times and extends functional test coverage for a broader range of low-end SOC devices than the traditional J750 platform. Another key component of the J750, Teradyne IG-XL™ software, reduces program development time for multisite production release and continues to be a benchmark for ATE software.

"The J750Ex instrumentation can test increasingly complex devices while delivering the high production volume and low cost of test required in the price sensitive consumer device arena." said Jason Zee, Consumer Business Unit manager, Teradyne. "The J750 system's extensive instrument portfolio enables Unisem to serve a broad range of semiconductor test applications including microcontrollers and consumer audio devices."

"The J750 system offers tremendous value to our customers who need an ATE platform that offers rapid time-to-market and low cost-of-test for semiconductors targeted at the consumer electronics market," said Marita Erickson, general manager, Unisem-Sunnyvale. "Adding the availability of J750Ex digital instrumentation extends the range of test coverage we can offer our customers."

#### **About Teradyne**

Teradyne (NYSE:TER) is the leading supplier of Automatic Test Equipment used to test complex electronics used in the consumer electronics, automotive, computing, telecommunications, and aerospace and defense industries. In 2010, Teradyne had sales of \$1.6 billion. For more information, visit [www.teradyne.com](http://www.teradyne.com). Teradyne® is a registered trademark of Teradyne, Inc. in the U.S. and other countries. All product names are trademarks of Teradyne, Inc. (including its subsidiaries) or their respective owners.

**About Unisem**

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 10,000 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at [www.unisemgroup.com](http://www.unisemgroup.com).

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